

## **BULT118D**

# HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- NPN TRANSISTOR
- INTEGRATED ANTIPARALLEL COLLECTOR-EMITTER DIODE
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

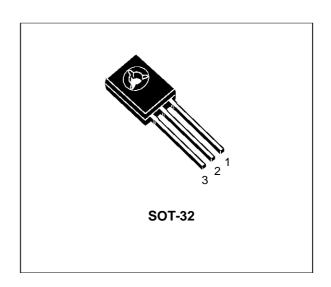
#### **APPLICATIONS:**

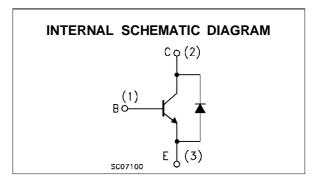
- ELECTRONIC BALLASTS FOR FLUORESCENT LIGHTING
- FLYBACK AND FORWARD SINGLE TRANSISTOR LOW POWER CONVERTERS



The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability. It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies.





#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-Emitter Voltage (V <sub>BE</sub> = 0)	700	V
Vceo	Collector-Emitter Voltage (I <sub>B</sub> = 0)	400	V
$V_{EBO}$	Emitter-Base Voltage (I <sub>C</sub> = 0)	9	V
Ic	Collector Current	2	Α
I <sub>CM</sub>	Collector Peak Current (tp < 5 ms)	4	Α
lΒ	Base Current	1	Α
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	2	Α
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	45	W
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Ti	Max. Operating Junction Temperature	150	°C

June 1997 1/7

#### THERMAL DATA

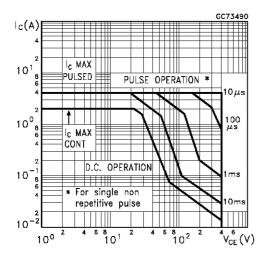
ſ	R <sub>thj-case</sub>	Thermal	Resistance	Junction-Case	Max	2.77	°C/W
	R <sub>thj-amb</sub>	Thermal	Resistance	Junction-Ambient	Max	80	°C/W

## **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25$ °C unless otherwise specified)

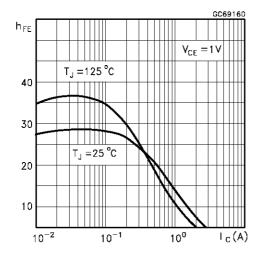
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = 700 V V <sub>CE</sub> = 700 V	T <sub>j</sub> = 125 °C			100 500	μA μA
V <sub>EBO</sub>	Emitter-Base Voltage	I <sub>E</sub> = 10 mA		9			V
V <sub>CEO(sus)</sub>	Collector-Emitter Sustaining Voltage	I <sub>C</sub> = 100 mA	L = 25 mH	400			V
I <sub>CEO</sub>	Collector-Emitter Leakage Current	V <sub>CE</sub> = 400 V				250	μА
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	$I_B = 0.1 A$ $I_B = 0.2 A$ $I_B = 0.4 A$			0.5 1 1.5	V V V
V <sub>BE(sat)*</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	I <sub>B</sub> = 0.1 A I <sub>B</sub> = 0.2 A I <sub>B</sub> = 0.4 A			1.0 1.2 1.3	V V V
h <sub>FE</sub> *	DC Current Gain	I <sub>C</sub> = 10 mA I <sub>C</sub> = 0.5 A I <sub>C</sub> = 2 A	V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V	10 10 8		50	
t <sub>r</sub> t <sub>s</sub>	RESISTIVE LOAD Rise Time Storage Time Fall Time	V <sub>CC</sub> = 125 V I <sub>B1</sub> = 0.2 A	I <sub>C</sub> = 1 A I <sub>B2</sub> = -0.2 A		0.4 3.2 0.25	0.7 4.5 0.4	μs μs μs
t <sub>s</sub>	INDUCTIVE LOAD Storage Time Fall Time	I <sub>C</sub> = 1 A V <sub>BE</sub> = -5 V V <sub>clamp</sub> = 300 V	I <sub>B1</sub> = 0.2 A L = 50 mH		0.8 0.16		μs μs

<sup>\*</sup> Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

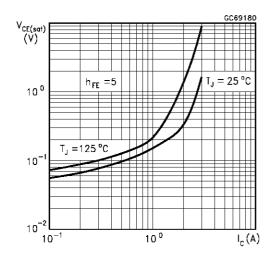
#### Safe Operating Areas



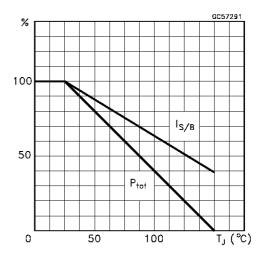
## DC Current Gain



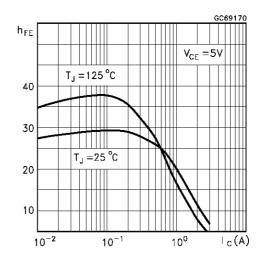
### Collector Emitter Saturation Voltage



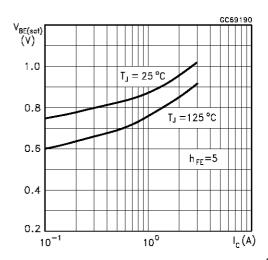
## **Derating Curve**



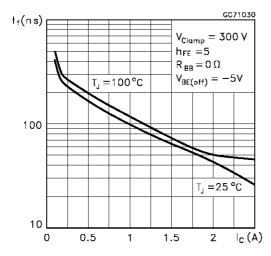
DC Current Gain



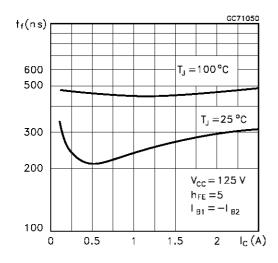
Base Emitter Saturation Voltage



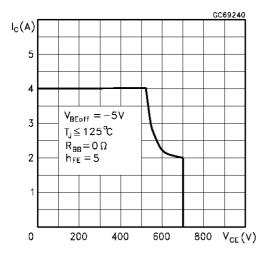
#### Inductive Fall Time



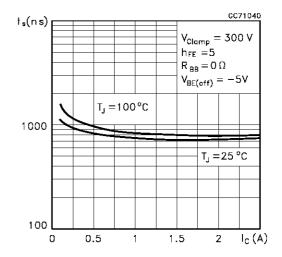
## Resistive Fall Time



#### Reverse Biased SOA



#### Inductive Storage Time



### Resistive Load Storage Time

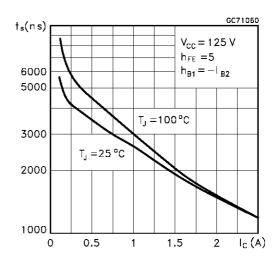


Figure 1: Inductive Load Switching Test Circuits.

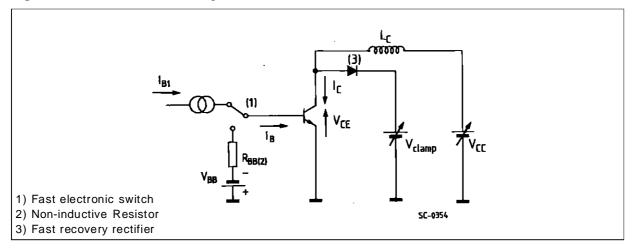
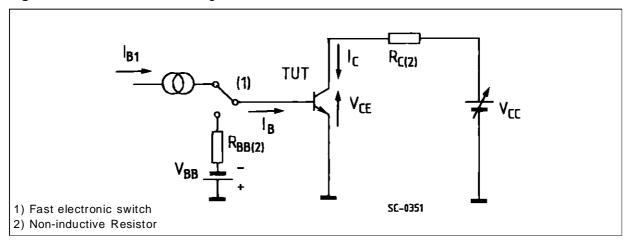
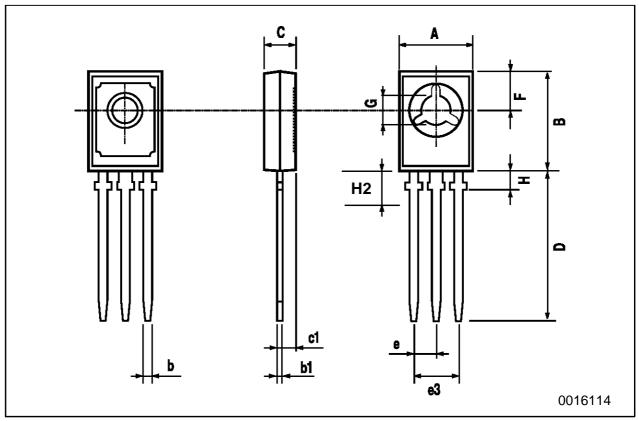


Figure 2: Resistive Load Switching Test Circuits.



# SOT-32 (TO-126) MECHANICAL DATA

DIM.	mm			inch			
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	7.4		7.8	0.291		0.307	
В	10.5		10.8	0.413		0.445	
b	0.7		0.9	0.028		0.035	
b1	0.49		0.75	0.019		0.030	
С	2.4		2.7	0.040		0.106	
c1	1.0		1.3	0.039		0.050	
D	15.4		16.0	0.606		0.629	
е		2.2			0.087		
e3	4.15		4.65	0.163		0.183	
F		3.8			0.150		
G	3		3.2	0.118		0.126	
Н			2.54			0.100	
H2		2.15			0.084		



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